

WE ARE
THE
PARTNER
FOR CUSTOMIZED WET PROCESS
EQUIPMENT



SpinStep *Flex line*

The modular, versatile single wafer system **SpinStep Flex line** is designed for etching, cleaning, lift-off, coating and developing

BENEFITS

- Modular design
- Customizable and extensible (i.e. semi- to fully automation, adaption of second process bowl)
- Different chemical supply systems are available
- Different processes in one bowl possible
- Easy to change the wafer size
- Optimized footprint
- Two tool sizes are available (Tool size 1: up to 200mm wafer, tool size 2: from 200 to 300mm wafers and substrates)
- User friendly and easy to use; operation and tool control via 15" touchpanel



APPLICATIONS

The SpinStep Flex line is designed for the following processes:

Semiconductor – Clean:

SC1, SC2, Piranha, DIW, Post CMP clean, DO-03

Semiconductor – Etch:

Etch / Siliziumoxid (Clean), Etch / Siliziumoxid, Etch Silizium

Semiconductor – Lift-off:

Our new lift-off process, patent pending

Semiconductor – Coating and developing:

Positiv negativ spray / puddle coating and developing

Semiconductor – Mask processor:

Cleaning, coating and developing



Mini Chemical Management System

- Mini Chemical Delivery System (MCDS)
- Mini Chemical Waste System (MCWS)
- Mini Chemical Mixing System (MCMS)
- Mini Chemical Recirculation System (MCRS)
- Mini Chemical Spiking System (MCSS)

Options

- Megasonic system (MEGPie, Nozzle)
- High-pressure system
- Single side brush
- Mixing nozzles
- Puddle nozzles
- Pre-Soak
- Chamber rinse
- Media heating system
- Programmable dispense arms
- Drain separation system
- Fire suppression system
- SECS II GEM Interface
- FM 4910 compliant
- Vacuum, low contact chuck
- Backside protection chuck
- Cool- / Hot-plate stacks
- HMDS primer module